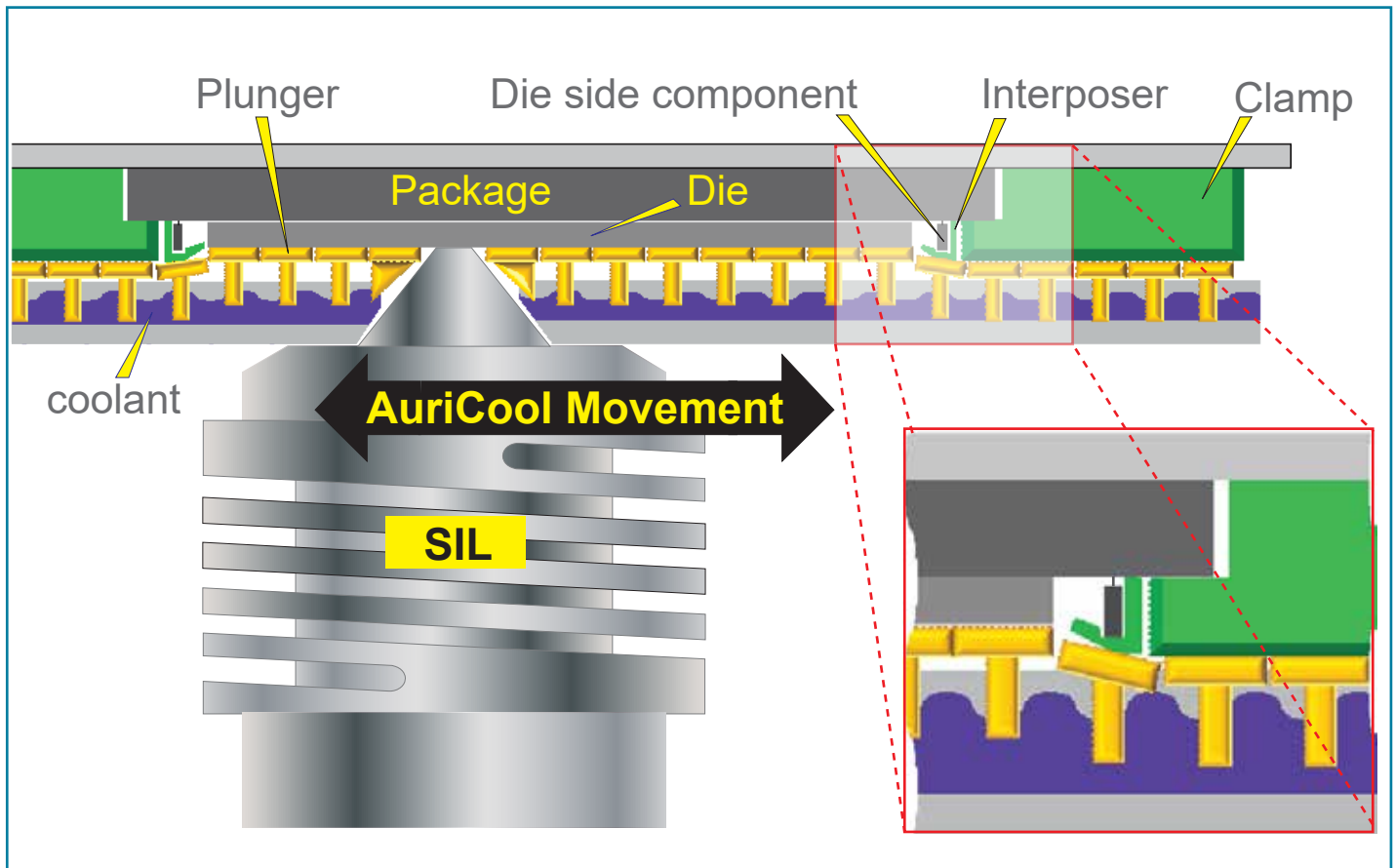


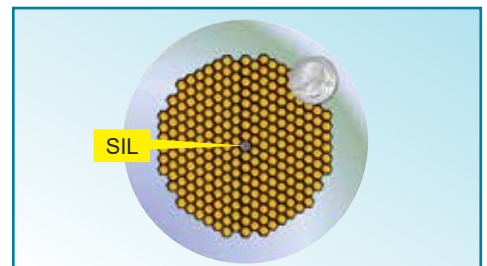
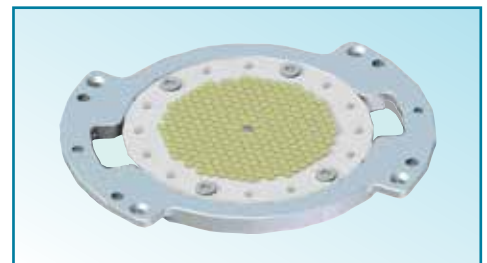
SEMICAPS AuriCool

The COOLING SYSTEM for DYNAMIC LASER TECHNIQUE & LASER WAVEFORM PROBING



Features

- Gold plated device to enhance thermal contact and conductivity
- Removes heat from active DUT during analysis
- Capable of handling up to 200 W of heat flux
- Compatible with SIL and air gap lenses with optical axis hole
- Does not require the silicon substrate to have high planarity
- Accommodates die-side components with flexible pins
- Best performance with water but can go below 0° C with glycol mix
- For use with all SEMICAPS platforms



AuriCool Head

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